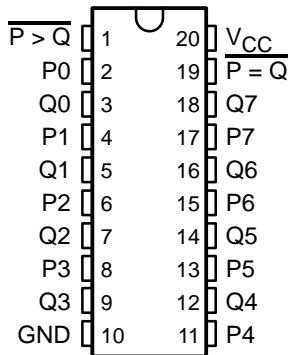


# SN54HC684, SN74HC684 8-BIT MAGNITUDE COMPARATORS

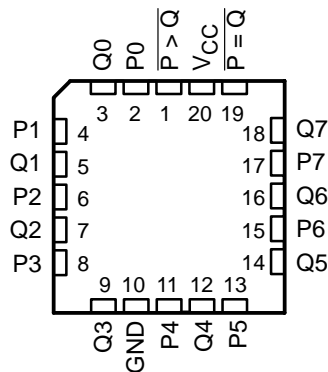
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 22$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Compare Two 8-Bit Words

SN54HC684 . . . J OR W PACKAGE  
SN74HC684 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54HC684 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These magnitude comparators perform comparisons of two 8-bit binary or BCD words. These devices provide  $P = Q$  and  $P > Q$  outputs.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74HC684N	HC684
	SOIC – DW	Tube	SN74HC684DW	
		Tape and reel	SN74HC684DWR	
-55°C to 125°C	CDIP – J	Tube	SNJ54HC684J	SNJ54HC684J
	CFP – W	Tube	SNJ54HC684W	SNJ54HC684W
	LCCC – FK	Tube	SNJ54HC684FK	SNJ54HC684FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE

DATA INPUTS P, Q	OUTPUTS	
	$\overline{P = Q}$	$\overline{P > Q}$
$P = Q$	L	H
$P > Q$	H	L
$P < Q$	H	H

The  $P < Q$  function can be generated by applying  $\overline{P = Q}$  and  $\overline{P > Q}$  to a 2-input NAND gate.



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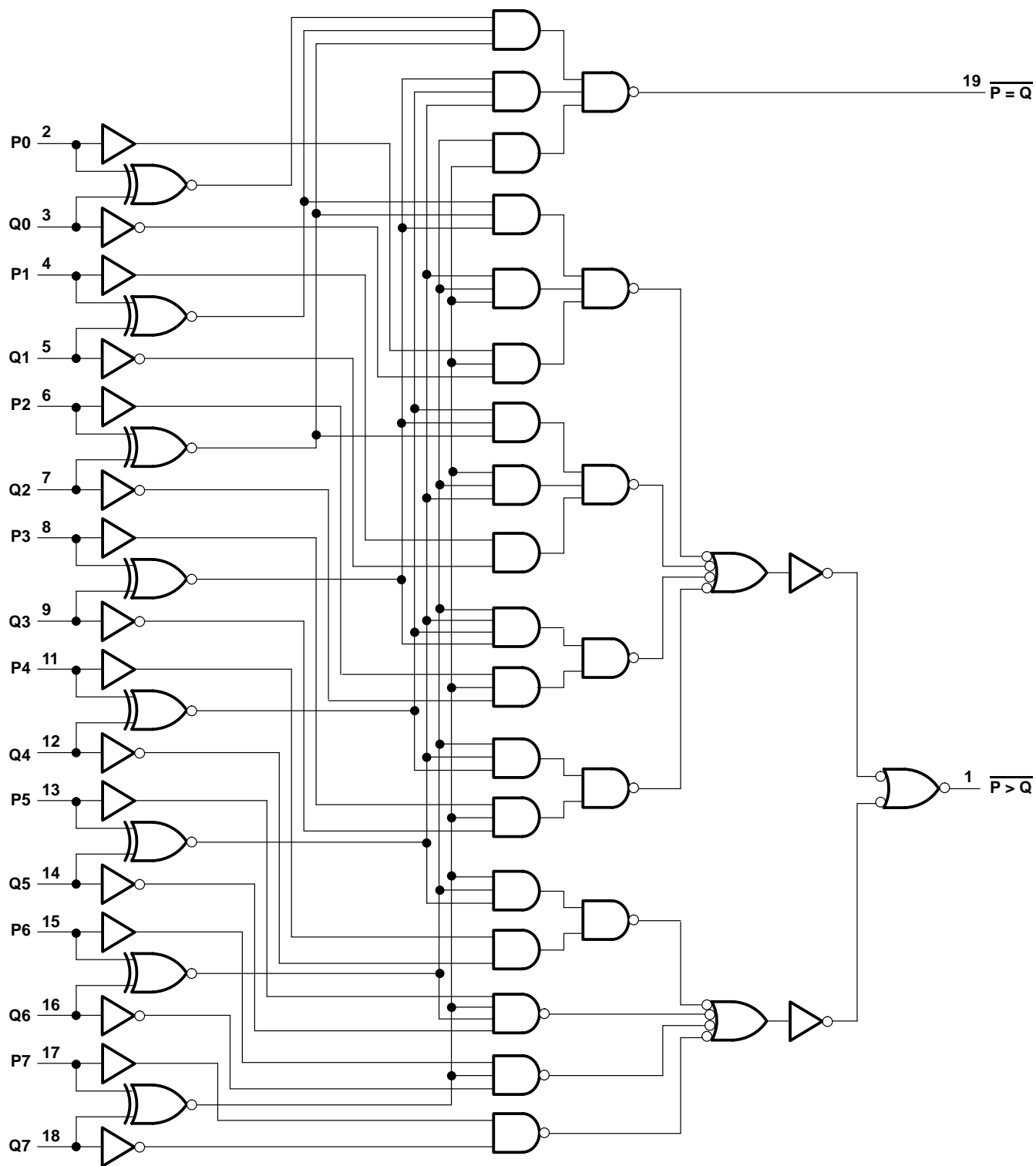
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# SN54HC684, SN74HC684 8-BIT MAGNITUDE COMPARATORS

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## logic diagram (positive logic)



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# SN54HC684, SN74HC684 8-BIT MAGNITUDE COMPARATORS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 7 V
Output voltage range, $V_O$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±25 mA
Continuous current through $V_{CC}$ or GND .....	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package .....	58°C/W
N package .....	69°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

		SN54HC684			SN74HC684			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V		1.5	$V_{CC} = 2$ V		1.5	V
		$V_{CC} = 4.5$ V		3.15	$V_{CC} = 4.5$ V		3.15	
		$V_{CC} = 6$ V		4.2	$V_{CC} = 6$ V		4.2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V			0.5	$V_{CC} = 2$ V		0.5
		$V_{CC} = 4.5$ V			1.35	$V_{CC} = 4.5$ V		1.35
		$V_{CC} = 6$ V			1.8	$V_{CC} = 6$ V		1.8
$V_I$	Input voltage	0		$V_{CC}$	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	0		$V_{CC}$	V
$t_t$	Input transition (rise and fall) times	$V_{CC} = 2$ V			1000	$V_{CC} = 2$ V		1000
		$V_{CC} = 4.5$ V			500	$V_{CC} = 4.5$ V		500
		$V_{CC} = 6$ V			400	$V_{CC} = 6$ V		400
$T_A$	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54HC684, SN74HC684 8-BIT MAGNITUDE COMPARATORS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC684		SN74HC684		UNIT				
				MIN	TYP	MAX	MIN	MAX	MIN	MAX					
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V					
			4.5 V	4.4	4.499		4.4		4.4						
			6 V	5.9	5.999		5.9		5.9						
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.30		3.7		3.84						
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.80		5.2		5.34						
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V				
			4.5 V		0.001	0.1		0.1		0.1					
			6 V		0.001	0.1		0.1		0.1					
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33					
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33					
I <sub>IH</sub>	V <sub>I</sub> = V <sub>CC</sub>		6 V		0.1	100		1000		1000	nA				
I <sub>IL</sub>	V <sub>I</sub> = 0		6 V		-0.1	-100		-1000		-1000	nA				
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V				8		160		80	μA			
C <sub>i</sub>			2 V to 6 V								3	10		10	pF

switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC684		SN74HC684		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	P or Q	Any	2 V		130	275		413		344	ns
			4.5 V		26	55		88		69	
			6 V		22	47		70		58	
t <sub>t</sub>		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T<sub>A</sub> = 25°C

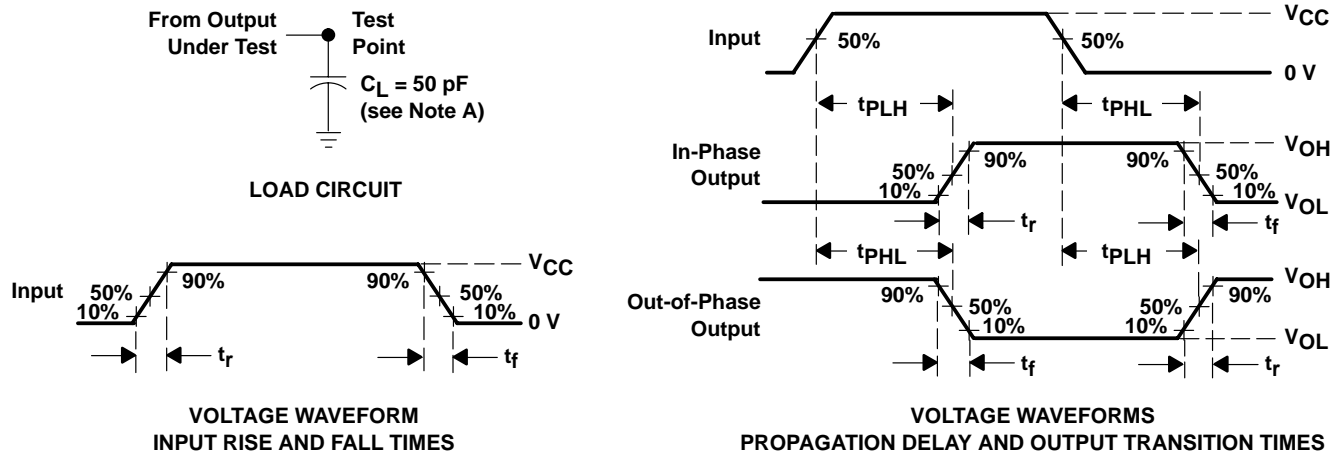
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load	40	pF

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.  
 D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC684DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC684	<a href="#">Samples</a>
SN74HC684DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC684	<a href="#">Samples</a>
SN74HC684N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC684N	<a href="#">Samples</a>
SN74HC684NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC684N	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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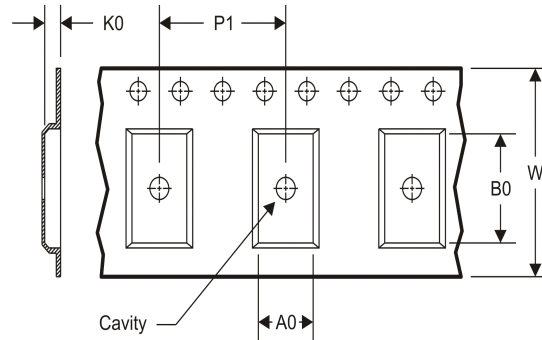
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**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC684DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1



**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC684DWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

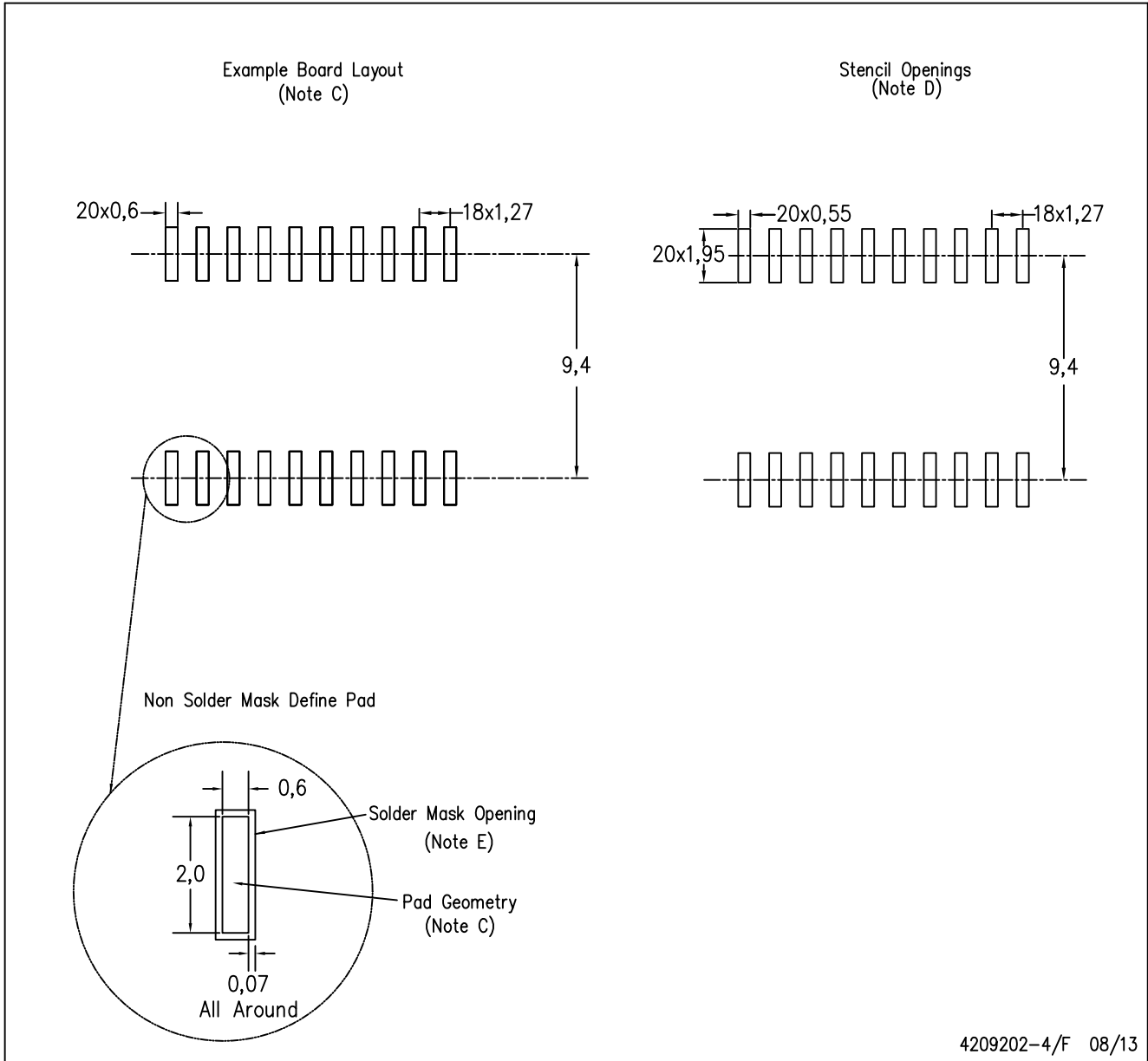
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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